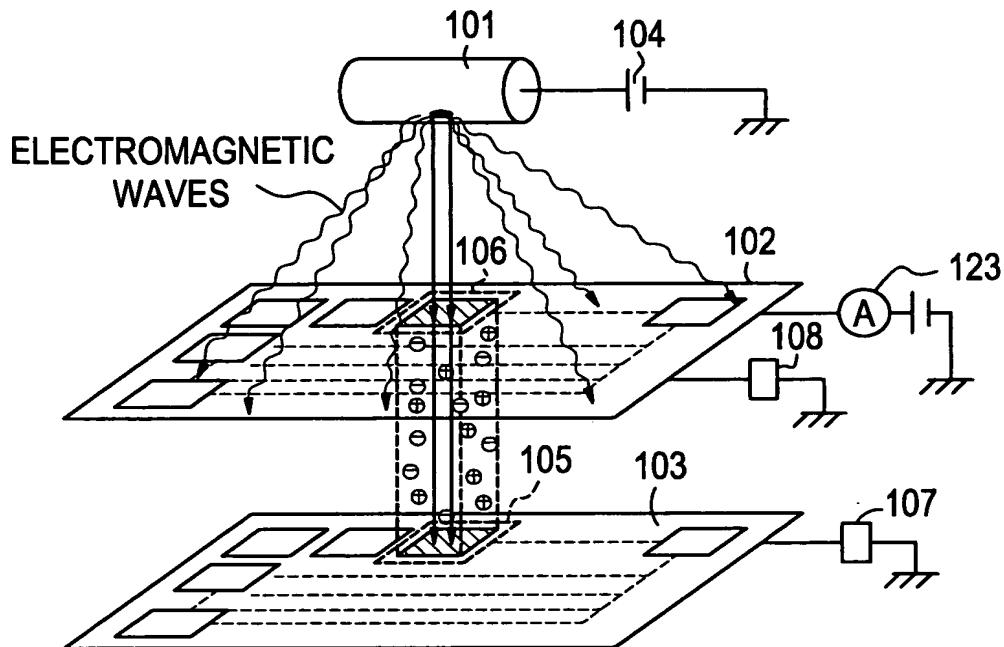
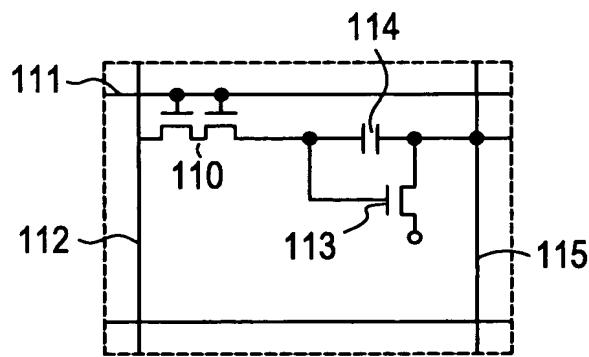


FIG. 1A**FIG. 1B**

ENLARGED DIAGRAM OF 105

**FIG. 1C**

ENLARGED DIAGRAM OF 106

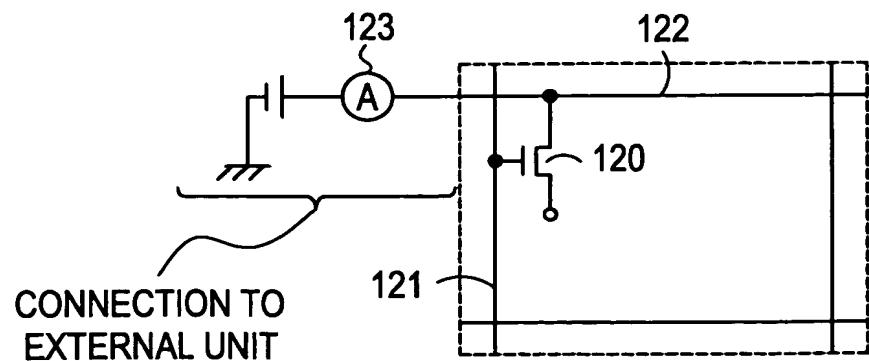


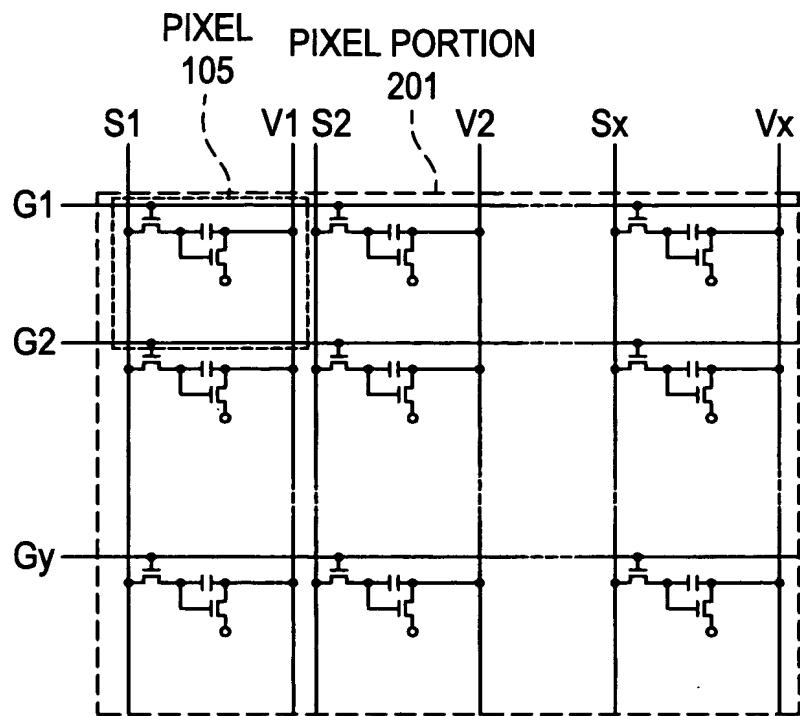
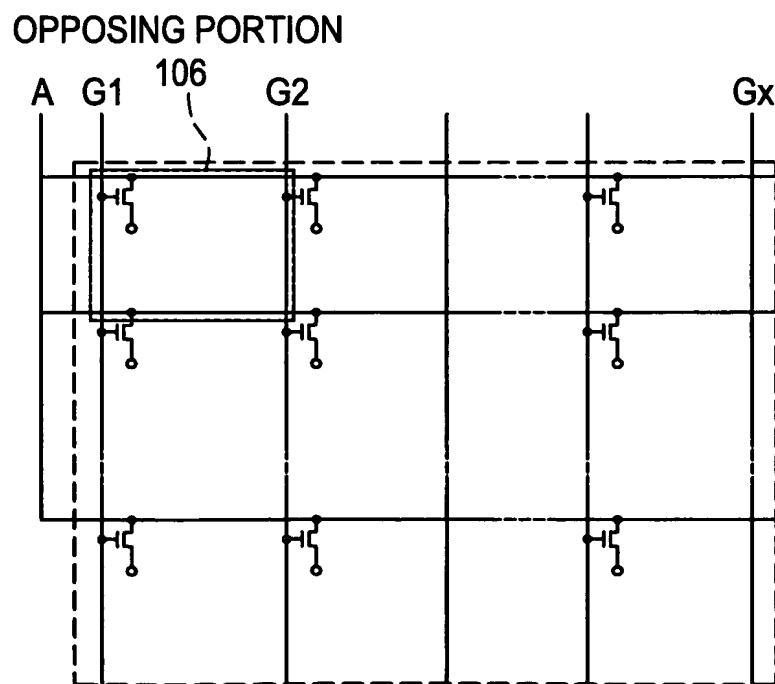
FIG. 2A**FIG. 2B**

FIG. 3A

(1, 1)	(2, 1)	(3, 1)	(4, 1)		(x-1, 1)	(x, 1)
(1, 2)	(2, 2)	(3, 2)	(4, 2)		(x-1, 2)	(x, 2)
(1, 3)	(2, 3)	(3, 3)	(4, 3)		(x-1, 3)	(x, 3)
(1, 4)	(2, 4)	(3, 4)	(4, 4)		(x-1, 4)	(x, 4)
(1, y-1)	(2, y-1)	(3, y-1)	(4, y-1)		(x-1, y-1)	(x, y-1)
(1, y)	(2, y)	(3, y)	(4, y)		(x-1, y)	(x, y)

FIG. 3B

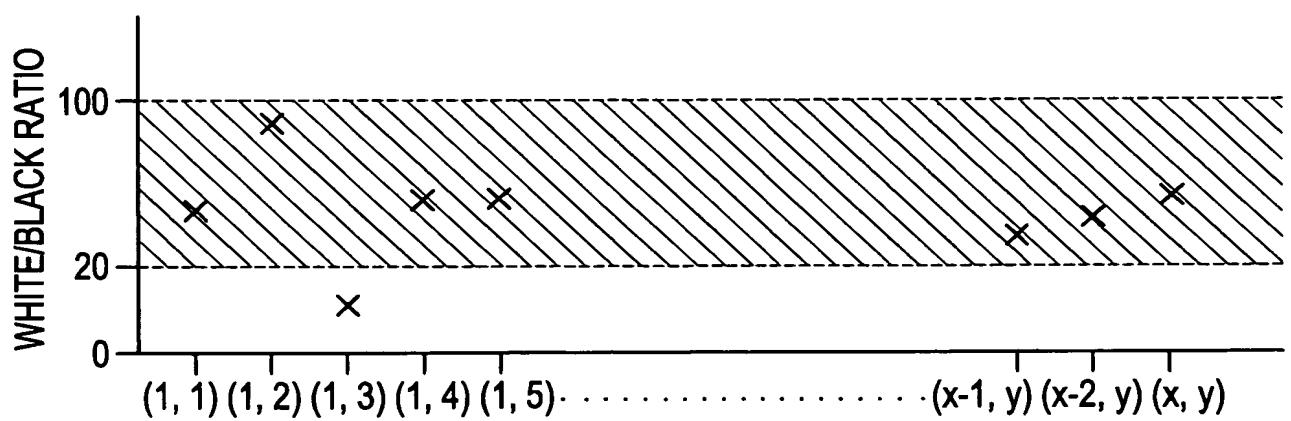
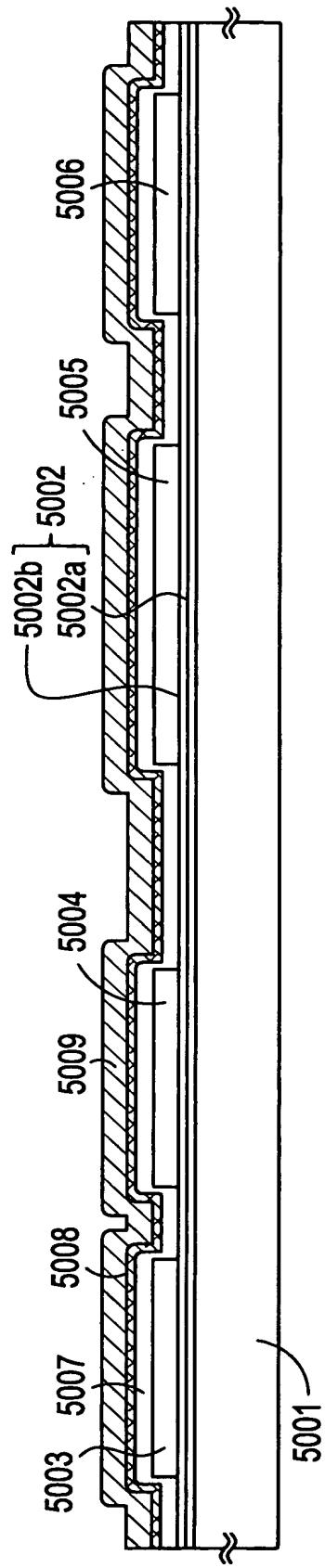


FIG. 4A

FORMATION OF ISLAND SEMICONDUCTOR LAYER, GATE-INSULATING FILM,
AND FIRST AND SECOND CONDUCTING FILMS FOR GATE ELECTRODES

**FIG. 4B**

FIRST ETCHING AND FIRST DOPING

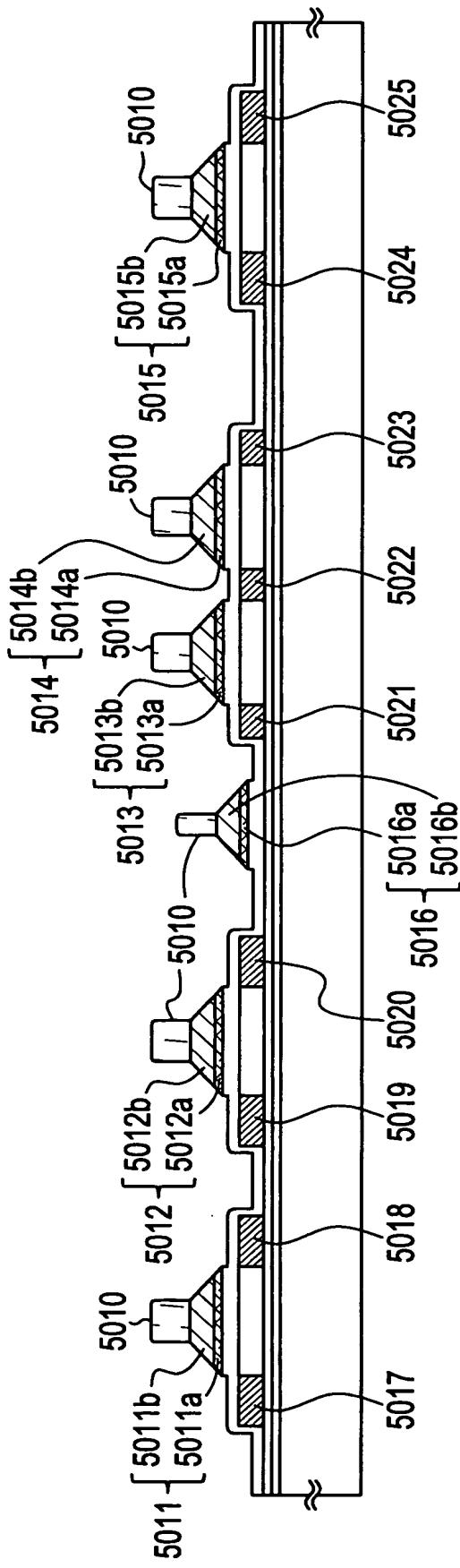


FIG. 4C
SECOND ETCHING

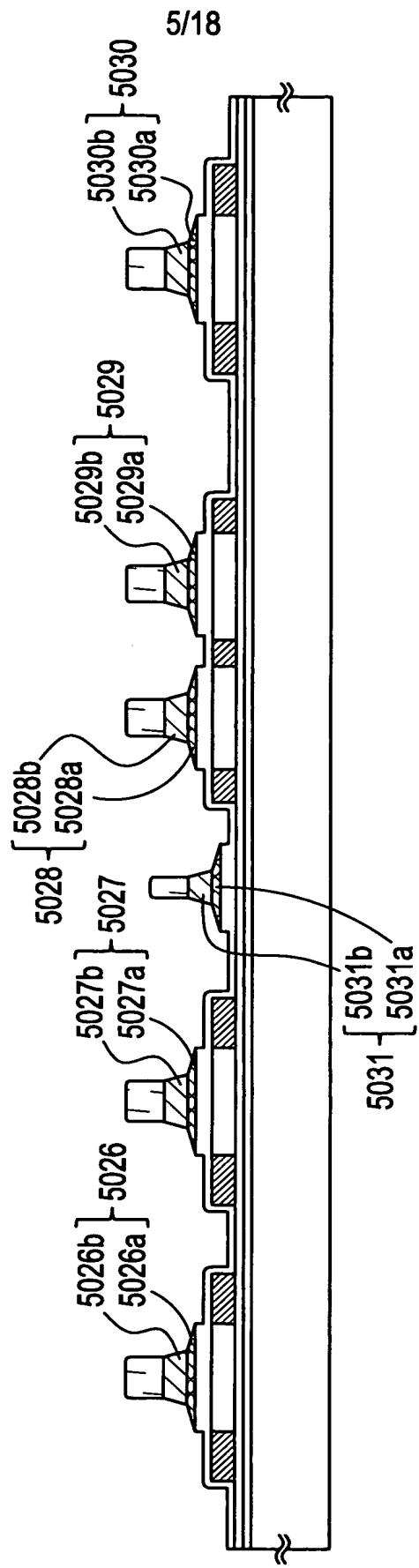


FIG. 5A
SECOND DOPING

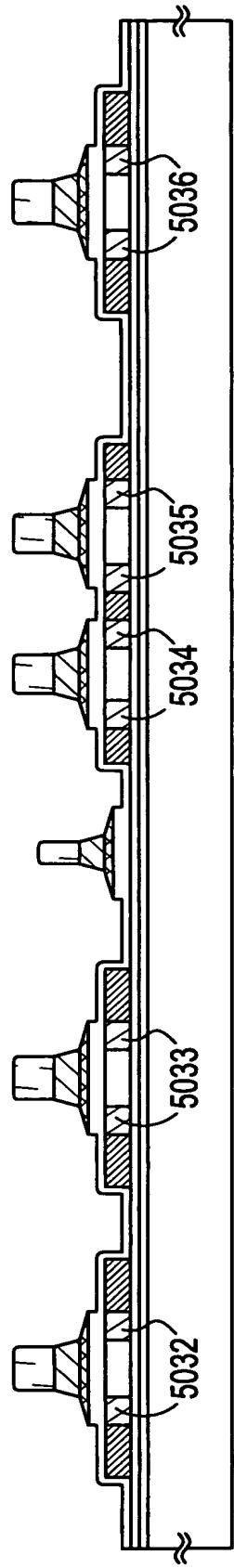


FIG. 5B
THIRD ETCHING

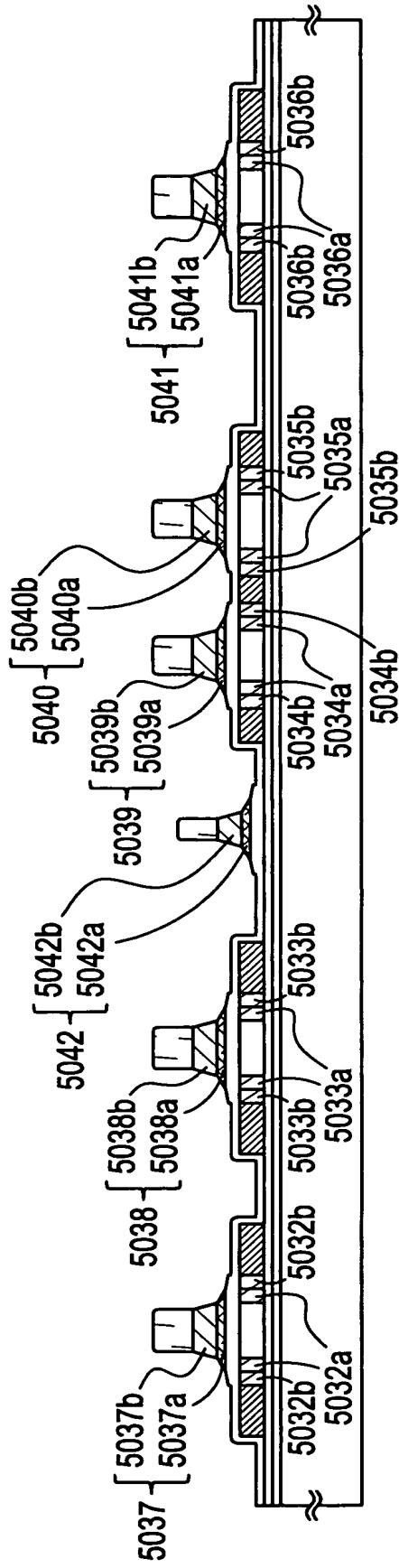


FIG. 5C
THIRD DOPING

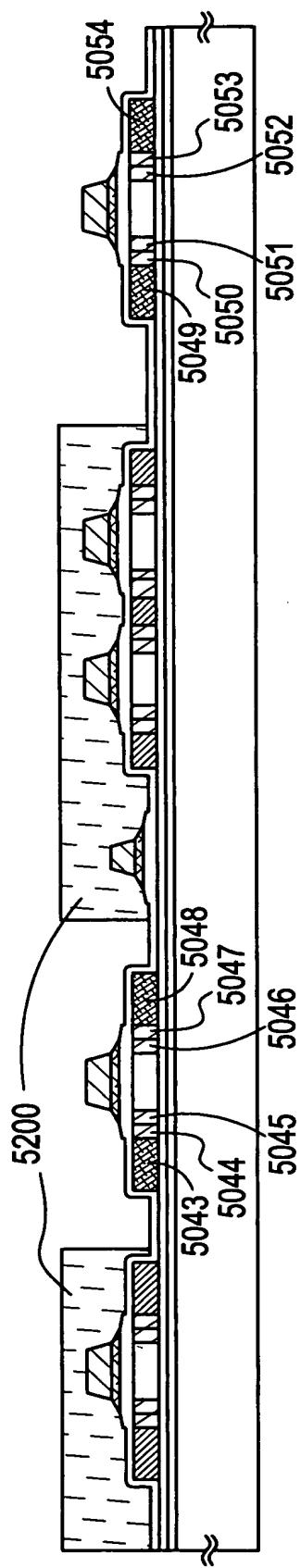
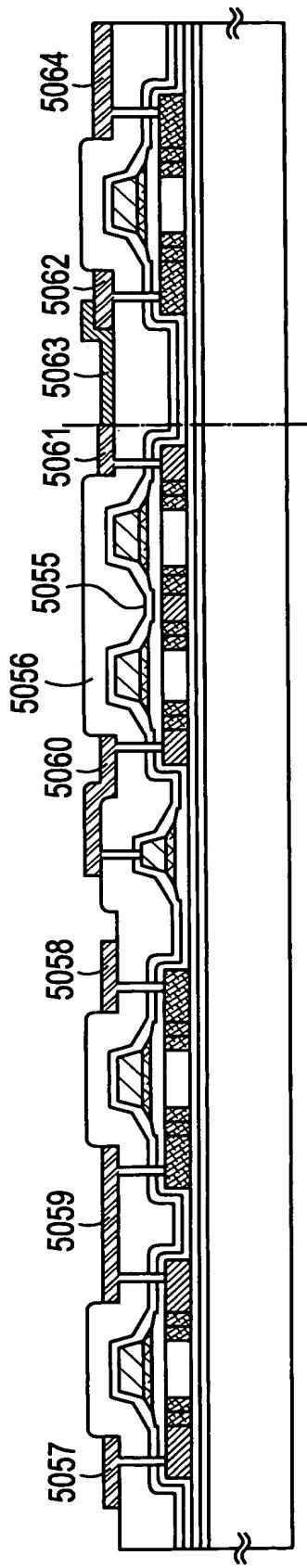


FIG. 6A

FORMATION OF THE FIRST AND SECOND INTERLAYER-INSULATING FILMS, WIRINGS AND PIXEL ELECTRODES

**FIG. 6B**

FORMATION OF THE THIRD INTERLAYER-INSULATING FILM, EL LAYER, CATHODES AND PASSIVATION FILM

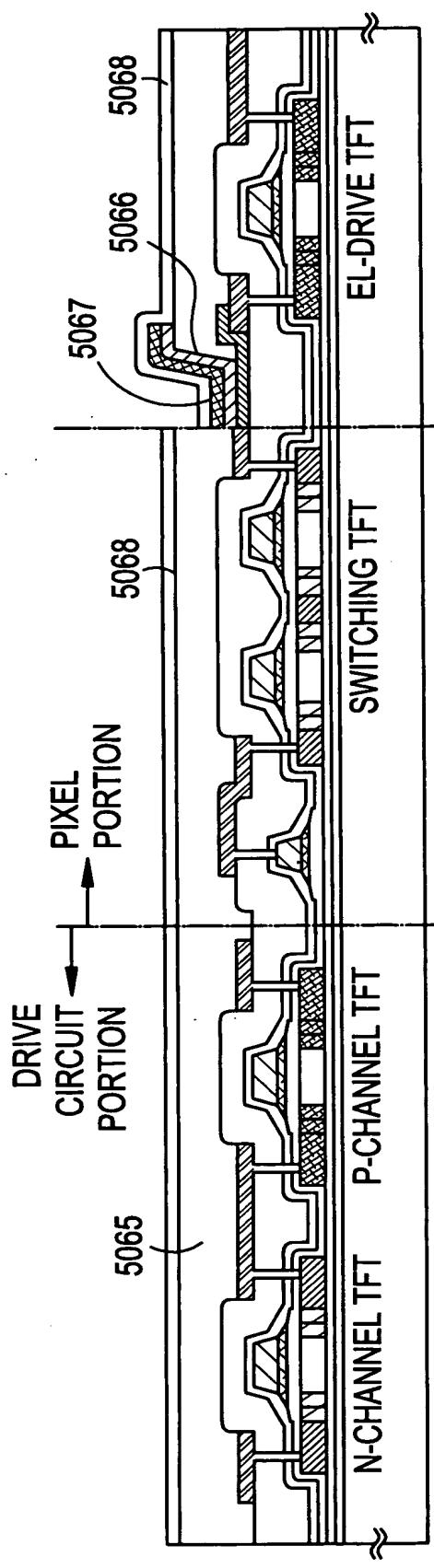


FIG. 7A

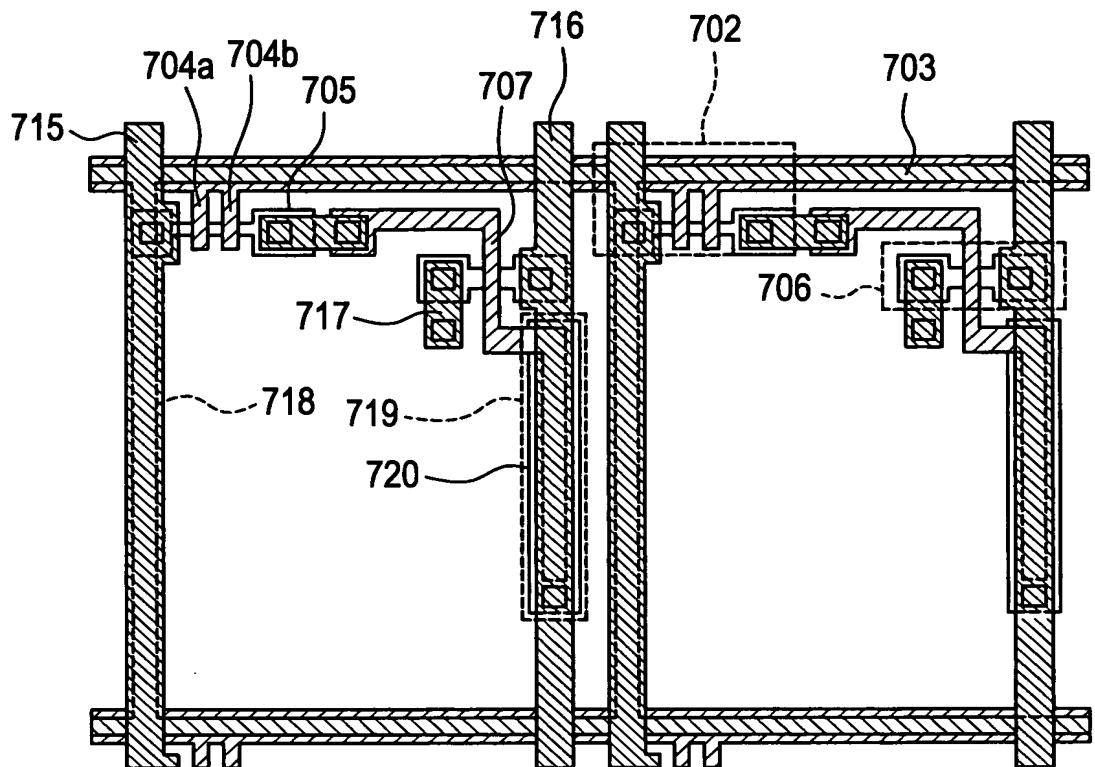


FIG. 7B

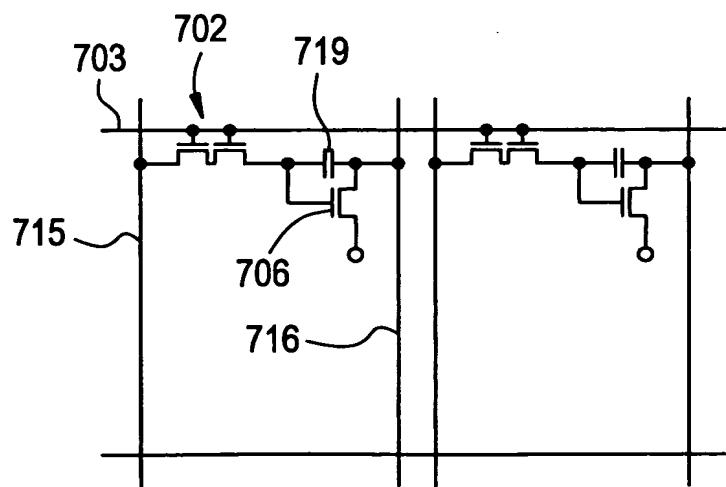


FIG. 8A

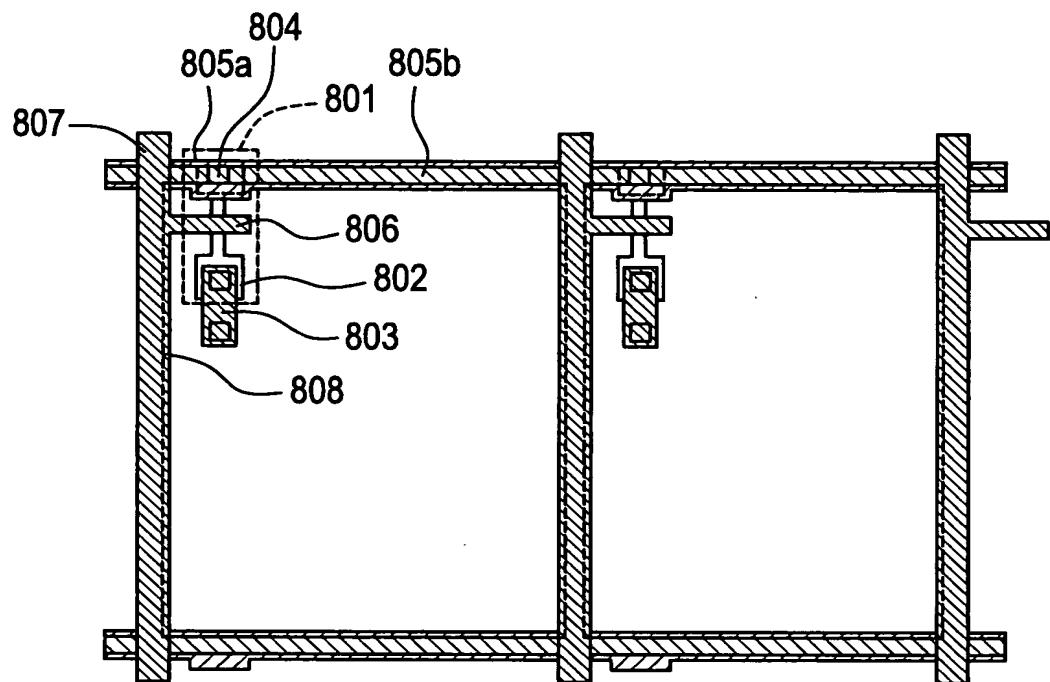


FIG. 8B

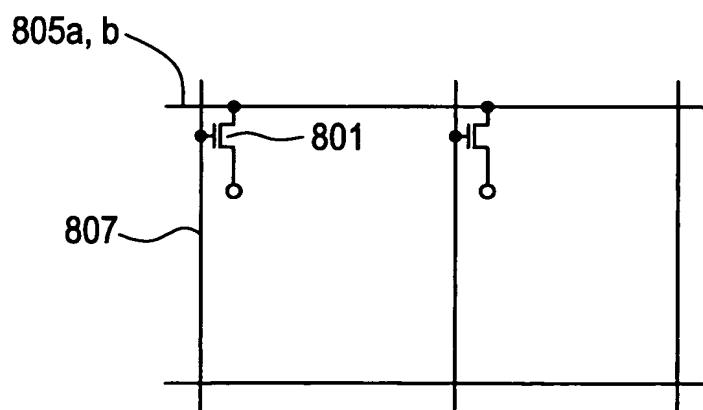


FIG. 9

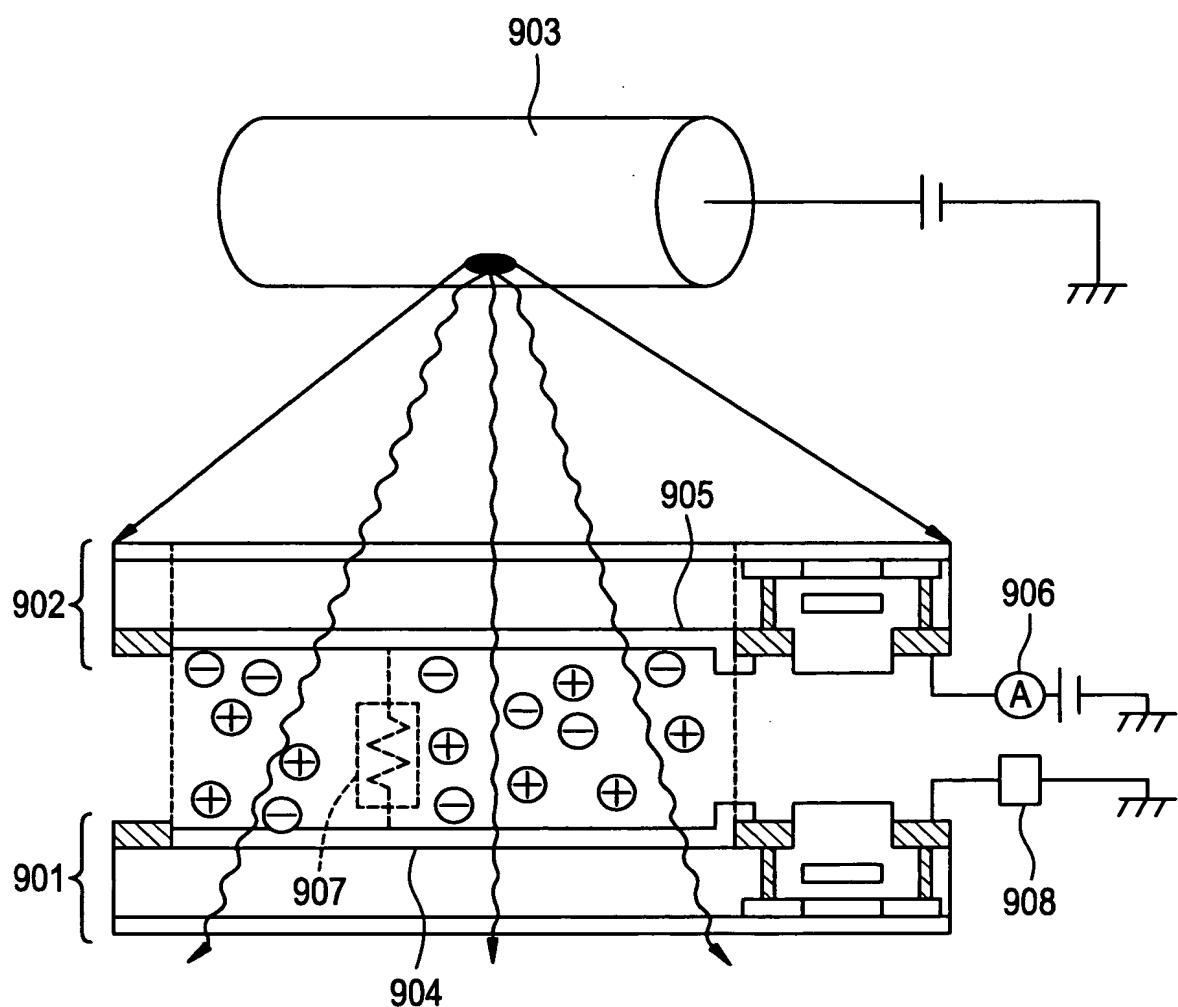


FIG. 10

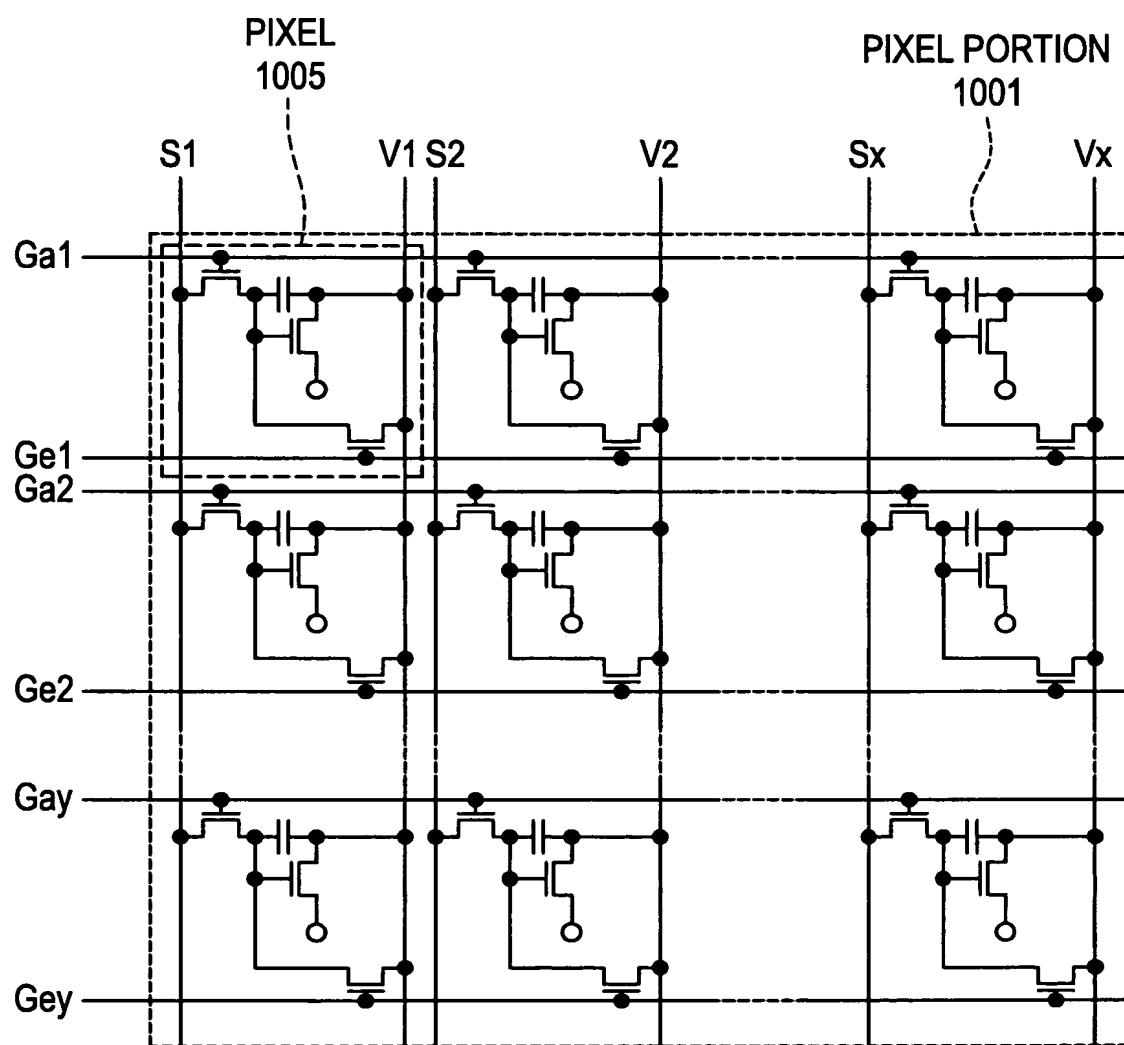


FIG. 11

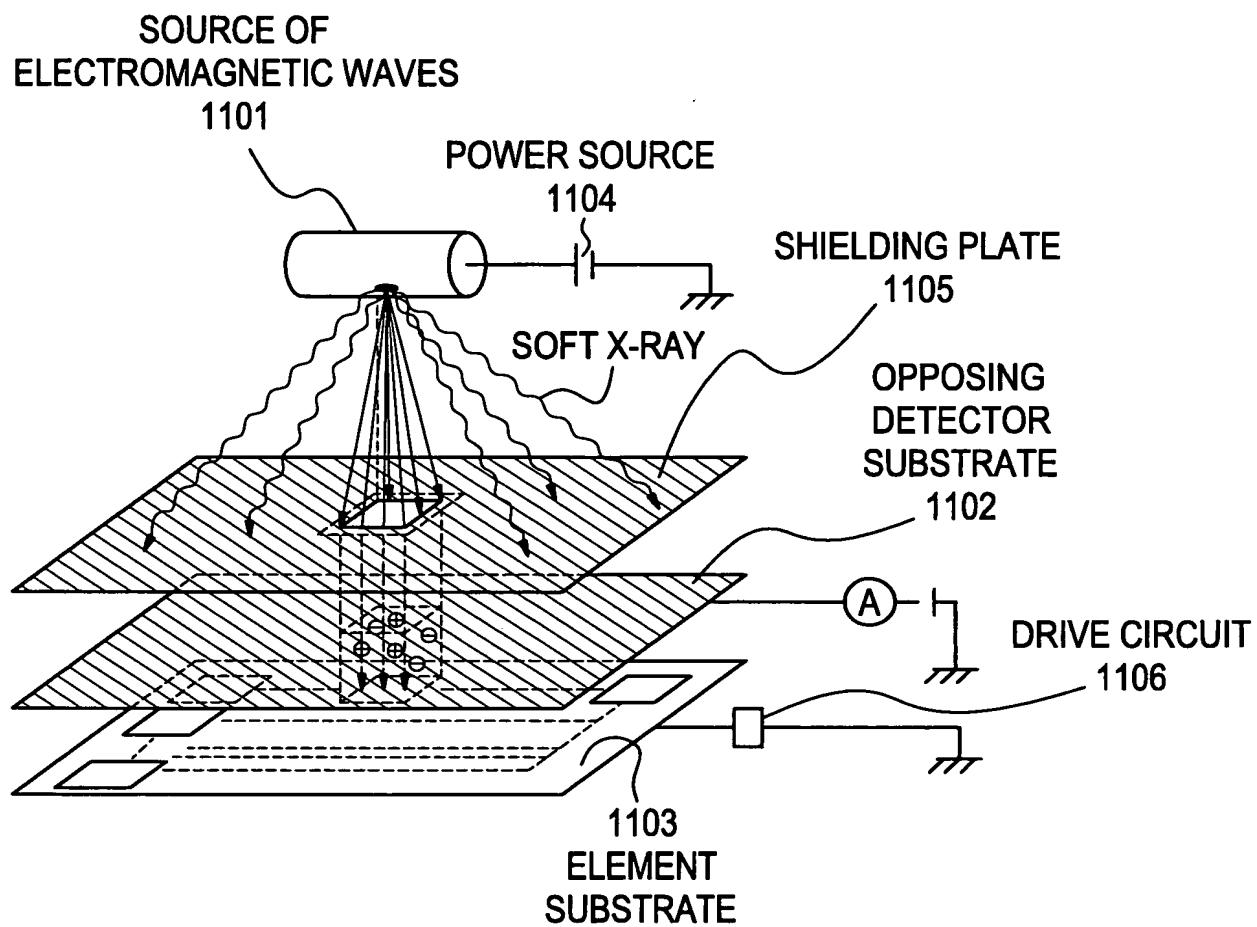


FIG. 12

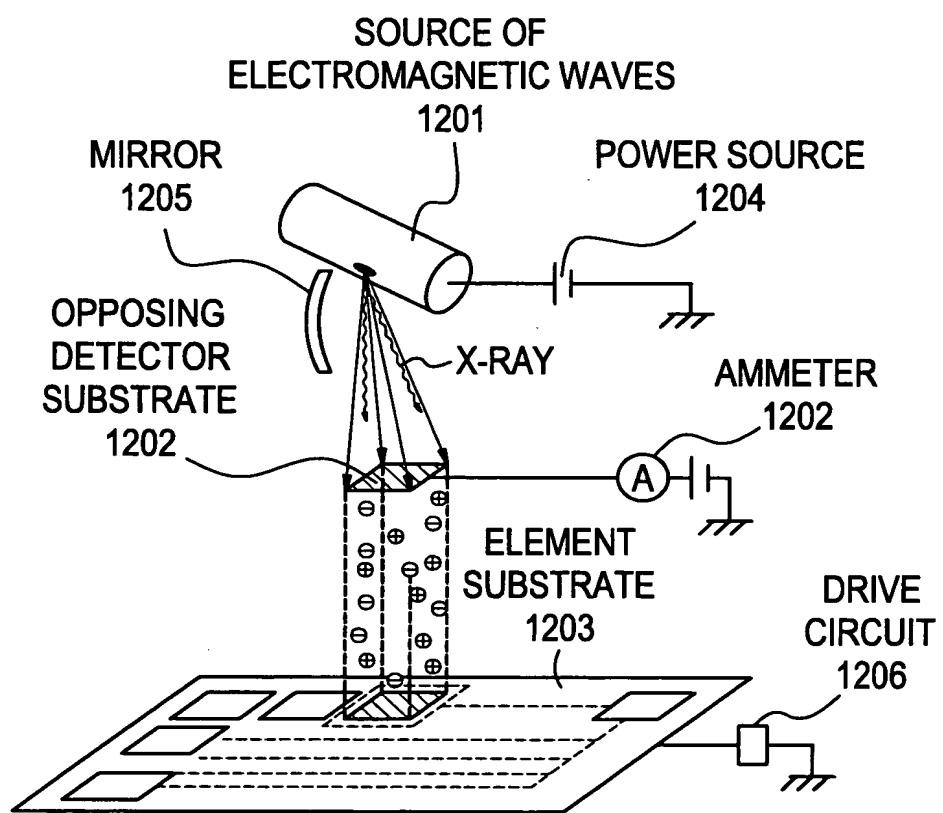


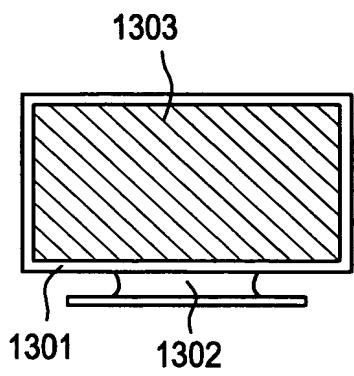
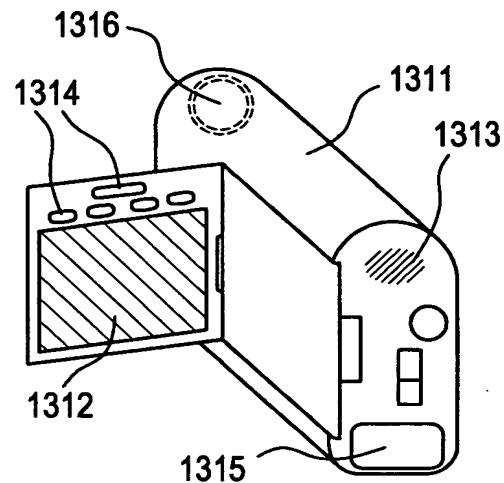
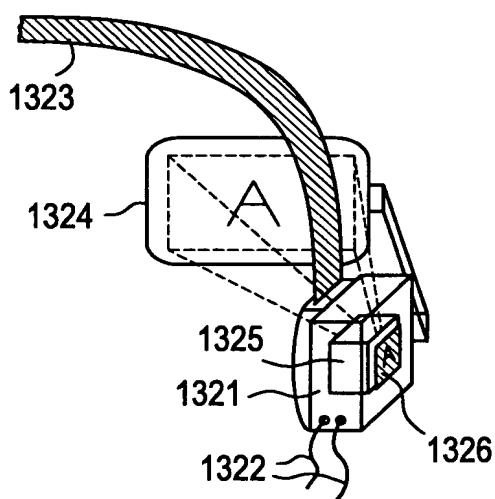
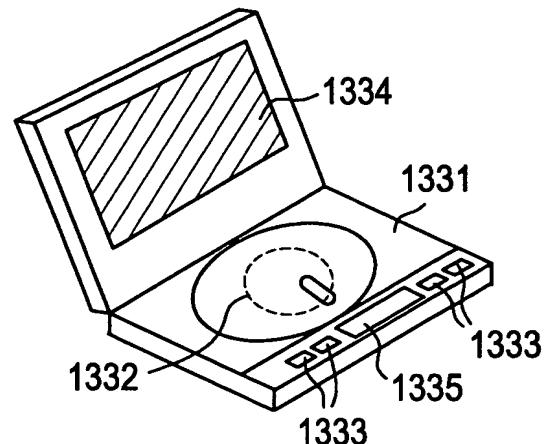
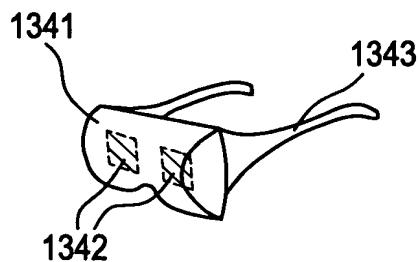
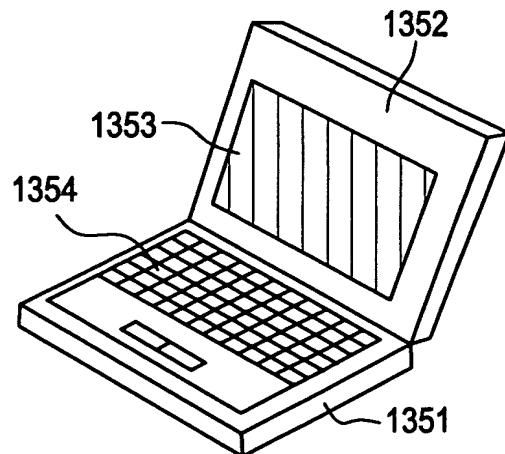
FIG. 13A**FIG. 13B****FIG. 13C****FIG. 13D****FIG. 13E****FIG. 13F**

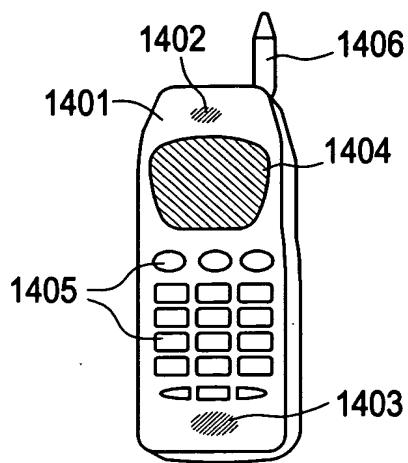
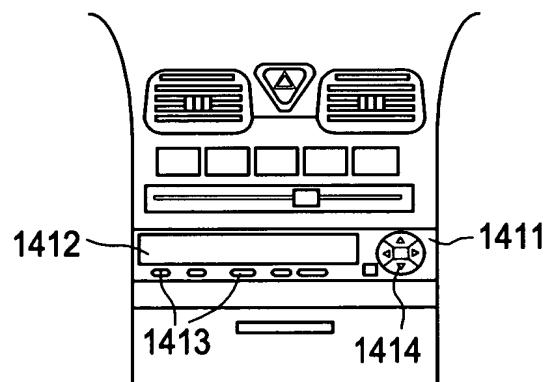
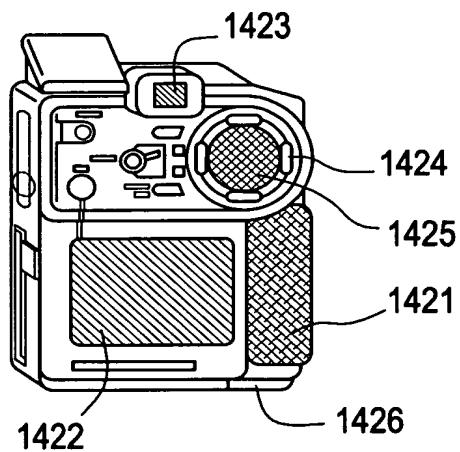
FIG. 14A**FIG. 14B****FIG. 14C**

FIG. 15

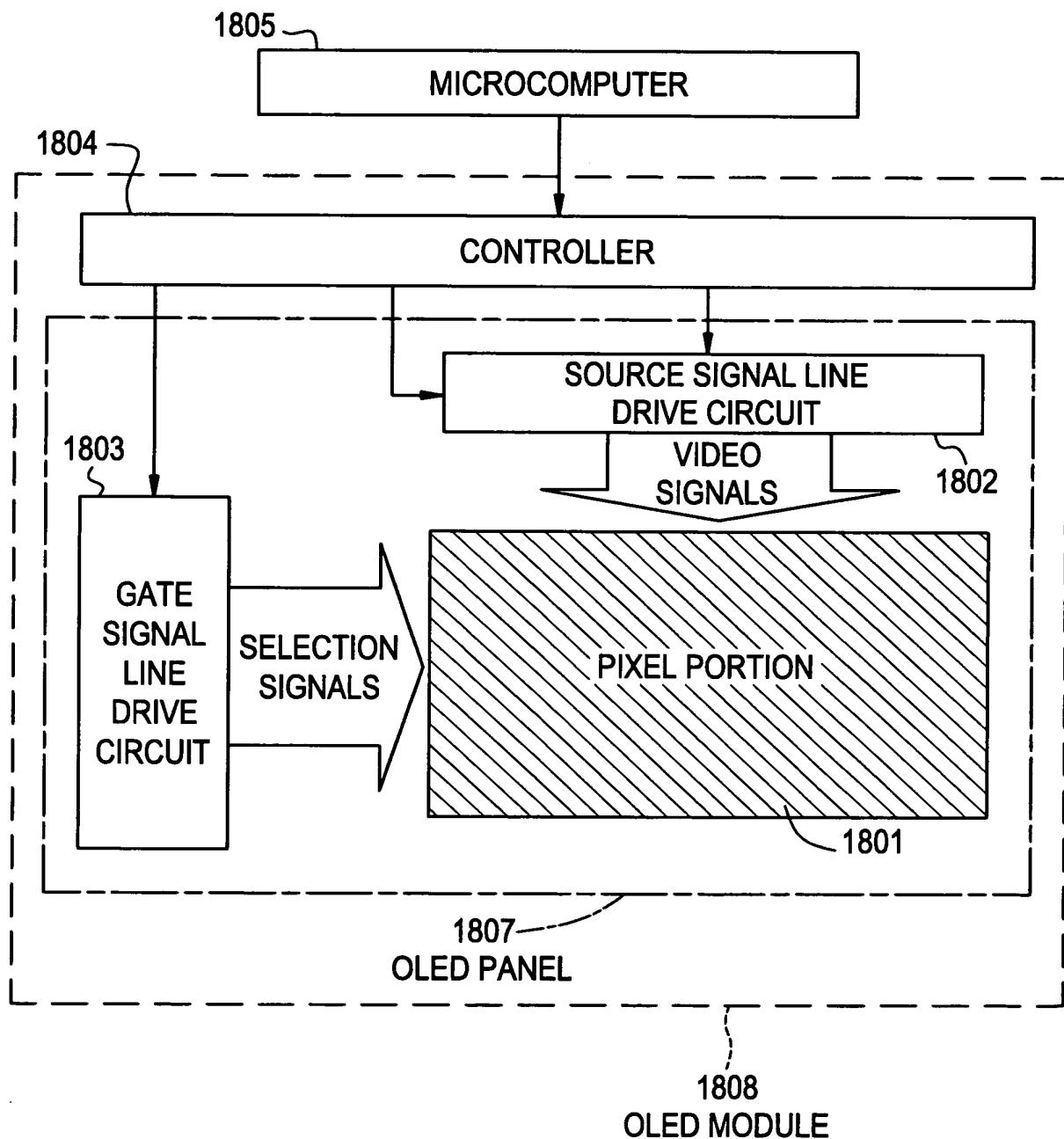


FIG. 16A

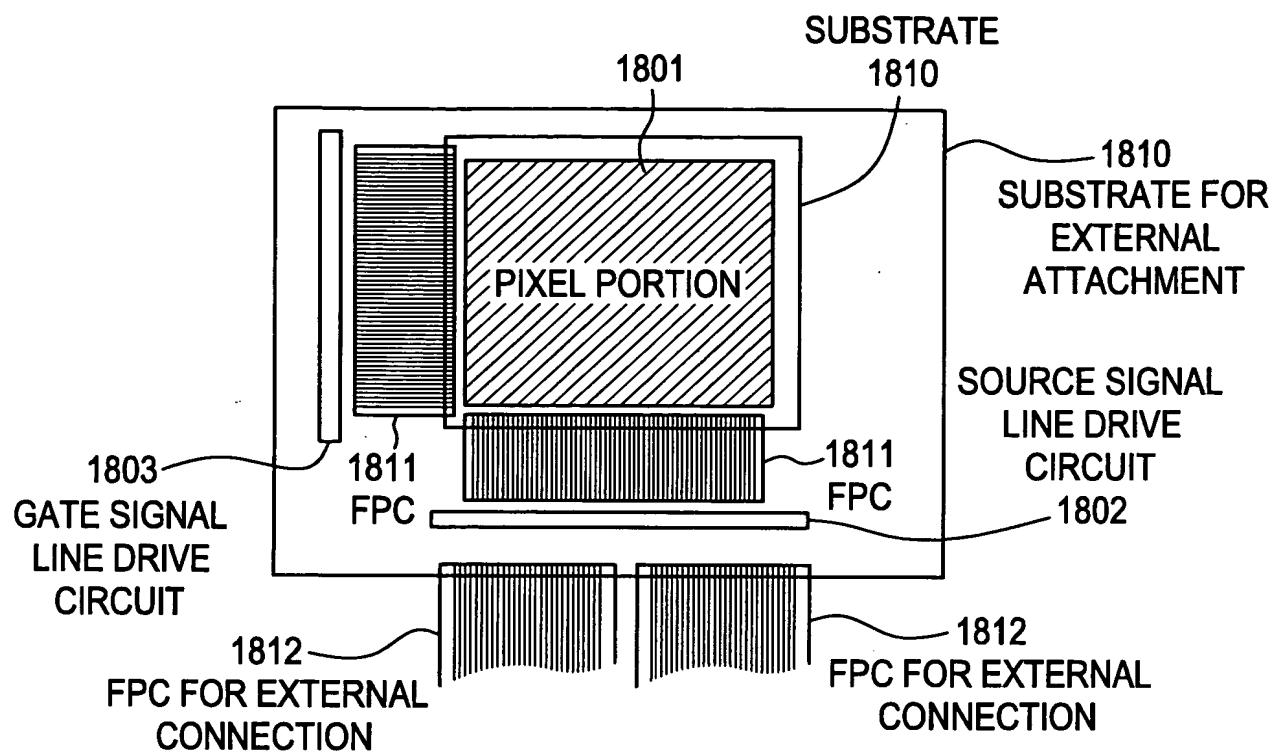


FIG. 16B

